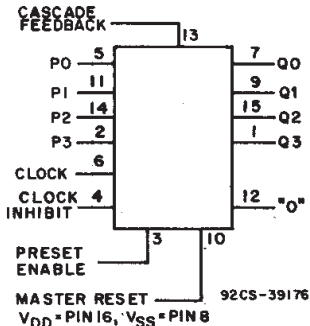


NOT RECOMMENDED FOR NEW DESIGNS

CD4522B Types

Advance Information/
Preliminary Data



FUNCTIONAL DIAGRAM

CMOS Programmable BCD Divide-by-“N” Counter

High-Voltage Types (20-Volt Rating)

Features:

- Internally synchronous for high internal and external speeds.
- Logic edge-clocked design — increments on positive Clock transition or on negative Clock Inhibit transition.
- 100% tested for quiescent current at 20-V.
- 5-V, 10-V, and 15-V parametric ratings.

- Standard symmetrical output characteristics.
- Maximum input current of 1 μ A at 18 V over full package-temperature range: 100 nA at 18 V and 25° C.
- Meets all requirements of JEDEC Standard No. 13B, “Standard Specifications for Description of ‘B’ Series CMOS Devices.”

■ CD4522B programmable BCD counter has a decoded “0” state output for divide-by-N applications. In single stage operation the “0” output is tied to the Preset Enable input. The Cascade Feedback allows multiple stage divide-by-N operation without the need for external gating. A HIGH on the Clock Inhibit disables the pulse-counting function. A HIGH on the Master Reset asynchronously resets the divide-by-N operation. The output is presented in BCD format.

Applications:

- Frequency synthesizers
- Phase-locked loops
- Programmable down counters
- Programmable frequency dividers

The CD4522B-series types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Voltages referenced to V_{SS} Terminal) -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to V_{DD} +0.5V

DC INPUT CURRENT, ANY ONE INPUT \pm 10mA

POWER DISSIPATION PER PACKAGE (P_D):

For T_A = -55°C to +100°C 500mW

For T_A = +100°C to +125°C Derate Linearly at 12mW/°C to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW

OPERATING-TEMPERATURE RANGE (T_A) -55°C to +125°C

STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max +265°C

3
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HIGH VOLTAGE ICs

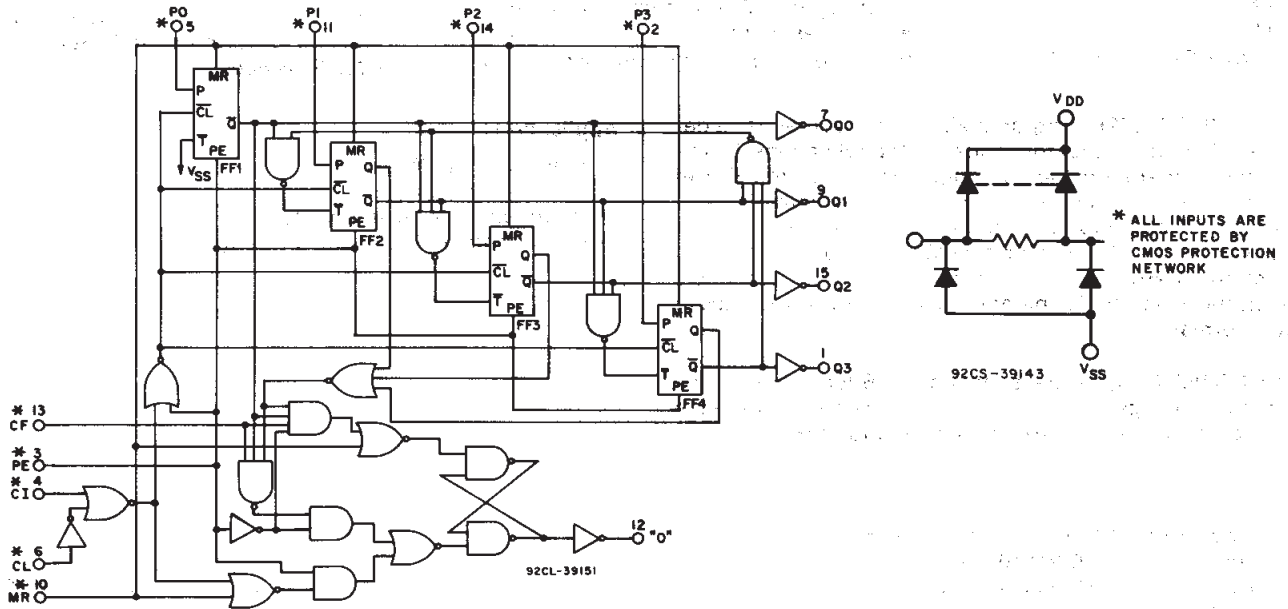
CD4522B Types

TRUTH TABLES

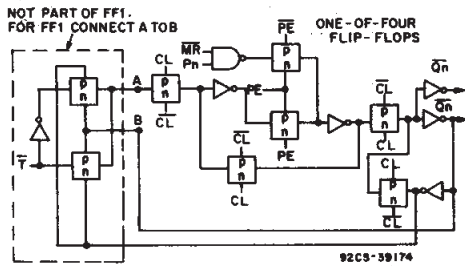
CLOCK	CLOCK INHIBIT	PRESET ENABLE	MASTER RESET	ACTION
0	0	0	0	No Count
0	0	0	0	Count Down
X	1	0	0	No Count
1	0	0	0	Count Down
X	X	1	0	Preset
X	X	X	1	Reset

X = Don't Care

Count	OUTPUTS			
	Q ₀	Q ₁	Q ₂	Q ₃
0	0	0	0	0
1	1	0	0	0
2	0	1	0	0
3	1	1	0	0
4	0	0	1	0
5	1	0	1	0
6	0	1	1	0
7	1	1	1	0
8	0	0	0	1
9	1	0	0	1



a. Basic diagram.



b. Flip-flop detail.

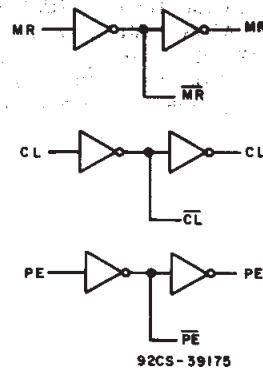


Fig. 1 - Logic diagram for the CD4522B.

CD4522B Types

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^\circ\text{C}$, except as noted.

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	V_{DD} (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For $T_A =$ Full Package-Temperature Range)		3	18	V
Pulse Width:	5	250	—	ns
Clock, $t_{w(cc)}$	10	100	—	
Preset Enable, $t_{w(cc)}$	15	80	—	
	5	250	—	ns
Preset Enable, $t_{w(cc)}$	10	100	—	
Master Reset, $t_{w(MR)}$	15	80	—	
	5	350	—	ns
Master Reset, $t_{w(MR)}$	10	250	—	
Master Reset, $t_{w(MR)}$	15	200	—	
Clock Frequency, f_{CL}	5	—	1.5	MHz
	10	—	3.0	
	15	—	4.0	
Clock Rise and Fall Time t_{rCL}, t_{fCL}	5	—	15	μs
	10	—	15	
	15	—	15	
Preset Enable Set-up Time, t_{su}	5	0	—	ns
	10	0	—	
	15	0	—	
Preset Enable Hold Time, t_h	5	75	—	ns
	10	25	—	
	15	20	—	
Master Reset Removal Time, t_{rem}	5	130	—	ns
	10	50	—	
	15	30	—	

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COMMERCIAL CMOS
HIGH VOLTAGE ICs

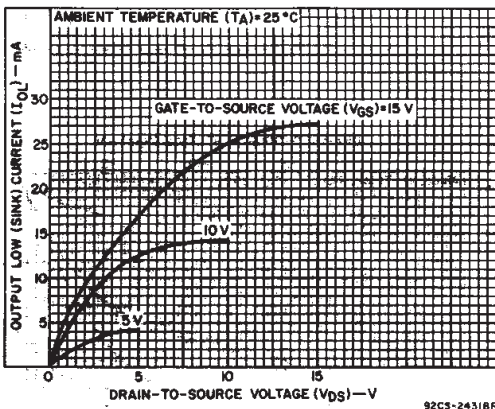


Fig. 2 — Typical output low (sink) current characteristics.

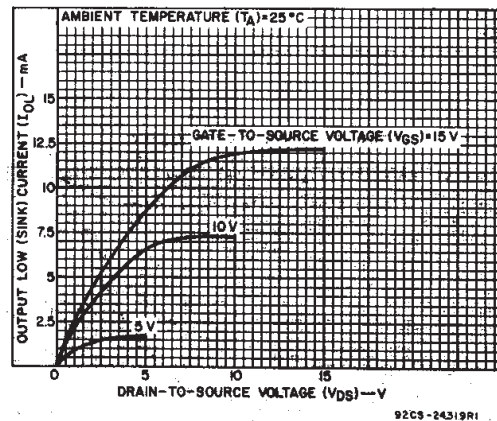
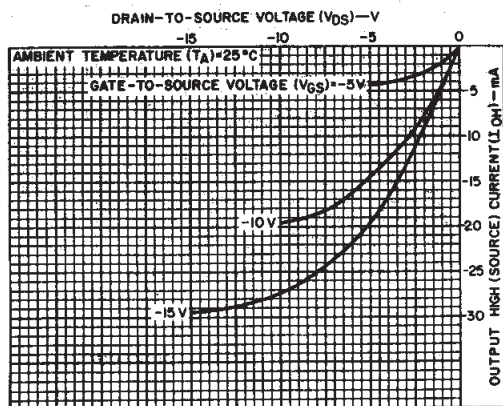


Fig. 3 — Minimum output low (sink) current characteristics.

CD4522B Types

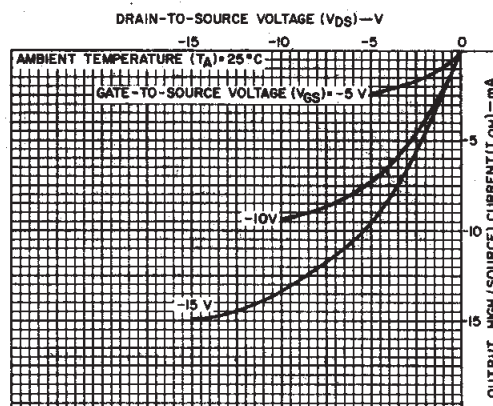
STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)					+25			
				-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0, 5	5	5	5	150	150	—	0.04	5	μA
	—	0, 10	10	10	10	300	300	—	0.04	10	
	—	0, 15	15	20	20	600	600	—	0.04	20	
	—	0, 20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I _{OL} Min.	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	—	
	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	
Output High (Source) Current, I _{OH} Min.	2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	mA
	9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
	—	0, 5	5	0.05				—	0	0.05	
Output Voltage: Low-Level, V _{OL} Max.	—	0, 10	10	0.05				—	0	0.05	V
	—	0, 15	15	0.05				—	0	0.05	
	—	0, 5	5	4.95				4.95	5	—	
Output Voltage: High-Level V _{OH} Min.	—	0, 10	10	9.95				9.95	10	—	V
	—	0, 15	15	14.95				14.95	15	—	
	0.5, 4.5	—	5	1.5				—	—	1.5	
Input low Voltage, V _{IL} Max.	1, 9	—	10	3				—	—	3	V
	1.5, 13.5	—	15	4				—	—	4	
	0.5, 4.5	—	5	3.5				3.5	—	—	
Input High Voltage, V _{IH} Min.	1, 9	—	10	7				7	—	—	V
	1.5, 13.5	—	15	11				11	—	—	
	—	0, 18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	



92CS-24520R3

Fig. 4 — Typical output high (source) current characteristics.



92CS-24321R2

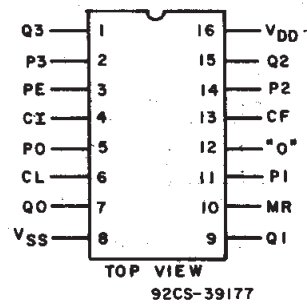
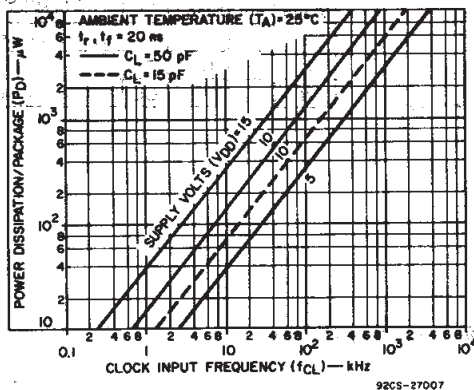
Fig. 5 — Minimum output high (source) current characteristics.

CD4522B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20\text{ ns}$, $C_i = 50\text{ pF}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS	
		V_{DD} (V)	Min.	Typ.		Max.
Propagation Delay Time; t_{PHL}, t_{PLH} Clock to "Q" outputs		5	—	550	1100	ns
		10	—	225	450	
		15	—	160	320	
Clock to "0" output		5	—	420	710	ns
		10	—	160	270	
		15	—	110	190	
Clock inhibit to "Q" outputs		5	—	270	540	ns
		10	—	100	200	
		15	—	70	140	
Master reset to "Q" outputs		5	—	270	540	ns
		10	—	100	200	
		15	—	70	140	
Preset Enable Setup Time, t_{su}		5	—	0	0	ns
		10	—	0	0	
		15	—	0	0	
Preset Enable Hold Time, t_h		5	—	75	150	ns
		10	—	25	50	
		15	—	20	40	
Master Reset Removal Time, t_{rem}		5	—	130	260	ns
		10	—	50	100	
		15	—	30	60	
Transition Time, t_{THL}, t_{TLH}		5	—	100	200	ns
		10	—	50	100	
		15	—	40	80	
Minimum Pulse Width Clock, $t_{W(CL)}$		5	—	125	250	ns
		10	—	50	100	
		15	—	40	80	
Preset Enable, $t_{W(PE)}$		5	—	125	250	ns
		10	—	50	100	
		15	—	40	80	
Master Reset, $t_{W(MR)}$		5	—	175	350	ns
		10	—	125	250	
		15	—	100	200	
Max Clock Freq, f_{CL}		5	—	3	1.5	MHz
		10	—	6	3.0	
		15	—	8	4.0	
Max Clock or Clock Inhibit Rise & Fall Time, t_{TLH}, t_{THL}		5	—	—	15	us
		10	—	—	15	
		15	—	—	15	
Input Capacitance, C_{IN}	Any Input		—	5	7.5	pF

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HIGH VOLTAGE ICs



TERMINAL ASSIGNMENT

Fig. 6 — Typical dynamic power dissipation vs. frequency.

CD4522B Types

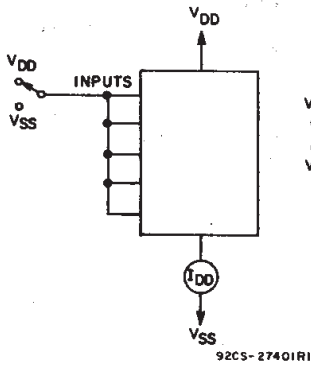


Fig. 7 — Quiescent device current test circuit.

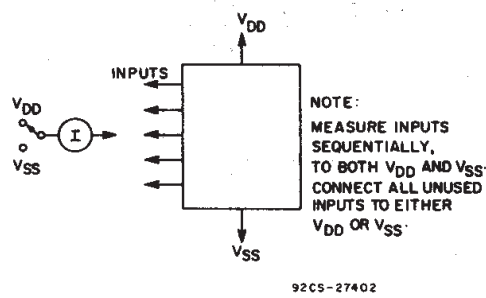


Fig. 8 — Input current test circuit.

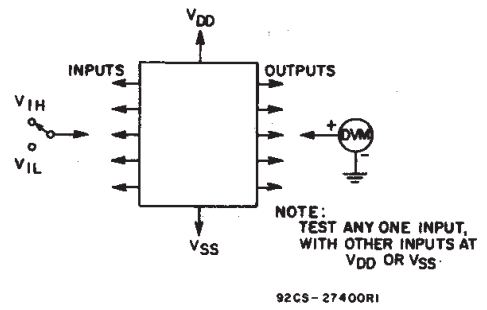


Fig. 9 — Input voltage test circuit.

APPLICATION CIRCUITS

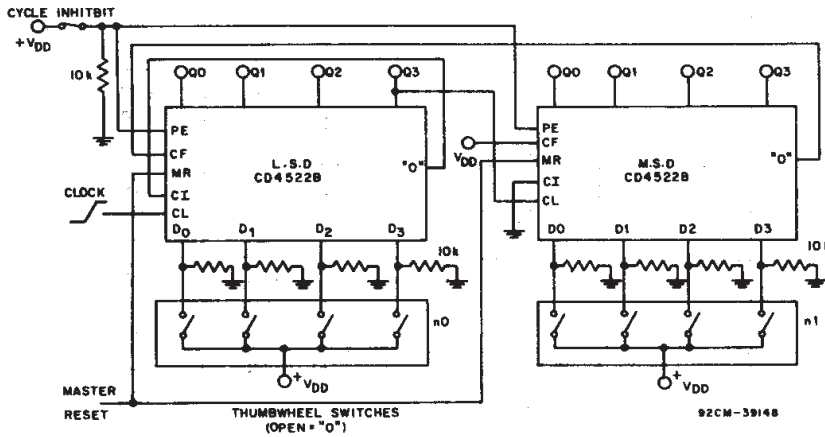


Fig. 10 — 2-Stage Programmable Down Counter (One Cycle)

From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0 ₃ "	N+1	CL	LSD < N < MSD-1

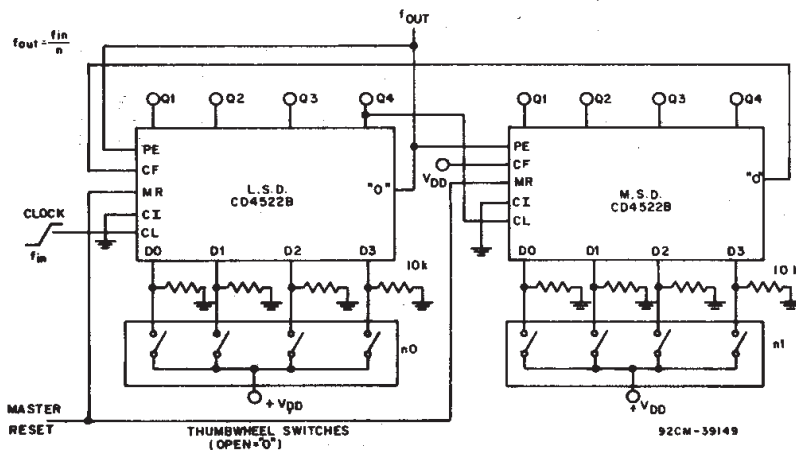
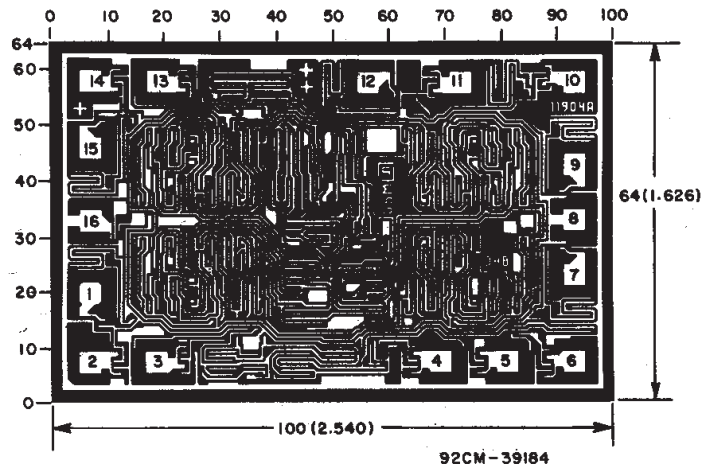


Fig. 11 — 2-Stage Programmable Frequency Divider

From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0 ₃ "	N+1	CL	LSD < N < MSD-1

CD4522B Types



Dimensions and pad layout for CD4522BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

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HIGH VOLTAGE ICs

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4522BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4522BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4522BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4522BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4522BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4522BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4522BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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